



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-02-14
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
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Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STPSC4G065UF	HB6Y*5D042T7	A	BO2A	2025-02-14
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	50	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
CHP	4.3x3.75	2	Flat
Comment			
Comment	6Y SMB Flat NEP		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	Description	

QueryList : California Prop65 list, dated 3rd January 2025			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.015	alloy	300

QueryList :Customer		Response
QUERY		Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
QUERY					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
Hazardous substance					
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE	
0	0	0	0	0	

QueryList : REACH-21st January 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
,	0		,	



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration :						Mfr Item Name	HB6Y*5D042T7		50.0010		6000001.0	1000020.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies or Wafer (choose)	M-011 Other inorganic materials	0.676	mg	supplier	die	Silicon(Si)	7440-21-3		0.635	mg	939349	12700
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.012	mg	17751	240
				supplier	metallisation	Gold(Au)	7440-57-5		0.006	mg	8876	120
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.015	mg	22189	300
				supplier	metallisation	Silver(Ag)	7440-22-4		0.002	mg	2959	40
				supplier	passivation	Silicon oxide	7631-86-9		0.006	mg	8876	120
Leadframe	M-004 Copper and its alloys	23.230	mg	supplier	alloy	Copper(Cu)	7440-50-8		23.199	mg	998666	463980
				supplier	alloy	Iron phosphide	26508-33-8		0.020	mg	861	400
				supplier	alloy	Iron(Fe)	7439-89-6		0.011	mg	474	220
Die attach	M-011 Other inorganic materials	0.224	mg	supplier	glue	Silver(Ag)	7440-22-4		0.204	mg	910714	4080
				supplier	glue	Bisphenol F type	9003-36-5		0.002	mg	8929	40
				supplier	glue	Thermoplastic resin	proprietary		0.011	mg	49107	220
				supplier	glue	additive	proprietary		0.007	mg	31250	140
Bonding wires	M-004 Copper and its alloys	0.280	mg	supplier	wire	Copper(Cu)	7440-50-8		0.280	mg	1000000	5600
Encapsulation	M-011 Other inorganic materials	25.438	mg	supplier	mold compound	Amorphous silicon	7631-86-9		22.512	mg	884975	450240
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		1.526	mg	59989	30520
				supplier	mold compound	Phenolic resin	9003-35-4		1.145	mg	45011	22900
				supplier	mold compound	Carbon black	1333-86-4		0.102	mg	4010	2040
				supplier	mold compound	Magnesium oxide	1309-48-4		0.051	mg	2005	1020
				supplier	mold compound	Aluminium hydroxide	21645-51-2		0.051	mg	2005	1020
Connections coating	Solder	0.153	mg	supplier	mold compound	Mercaptopropylamine	4420-74-0		0.051	mg	2005	1020
				supplier	solder alloy	Tin(Sn)	7440-31-5		0.153	mg	1000000	3060